

IN THE CLAIMS:

Claims 1-20 are pending.

Claims 1-9, 19, and 20 are cancelled.

Claims 10 and 11 are amended.

Claims 12-18 remain unchanged.

The status of the claims is as follows:

Claims 1-9 are cancelled.

Claim 10 (currently amended). A semiconductor packaging structure comprising:

a metal lead frame composed of an upper lead frame and a lower lead frame, wherein  
the upper lead frame has a first die pad, a first plurality of leads arranged around the  
first die pad, a first interval defined between the first die pad and the first plurality of leads,  
and a first plurality of gaps each is defined by an adjacent two of the first plurality of leads  
and is communicated with the first interval;

the lower lead frame has a second die pad, a second plurality of leads arranged  
around the second die pad, a second interval defined between the second die pad and the  
second plurality of leads, and a second plurality of gaps, each of the second plurality of  
gaps is defined by an two adjacent two of the second plurality of leads and is  
communicated with the second interval, wherein when the upper lead frame and the upper  
lower lead frame are compressed together, the first interval, the second interval, the first and  
the second plurality of gaps are communicated with each other for receiving an isolating  
resin;

a wall portion formed around a periphery of the upper lead frame;  
a chip mounted on the first die pad of the upper lead frame and electrically connected to the  
first plurality of leads; and  
a cover mounted on the wall portion to enclose the chip inside the wall portion.

11 (currently amended). The semiconductor packaging structure as claimed in claim 10, wherein  
the size of the second die pad is slightly smaller than that of the first die pad.

12 (original). The semiconductor packaging structure as claimed in claim 10, wherein each of the  
first plurality of leads has an external portion extending toward a flange of the upper lead frame, and  
has an internal portion extending toward the first die pad, each of the second plurality of leads  
corresponds to the external portion of one of the first plurality of leads.

13 (original) The semiconductor packaging structure as claimed in claim 11, wherein each of the  
first plurality of leads has an external portion extending toward a flange of the upper lead frame, and  
has an internal portion extending toward the first die pad, each of the second plurality of leads  
corresponds to the external portion of one of the first plurality of leads.

14 (original). The semiconductor packaging structure as claimed in claim 10, wherein the upper  
lead frame and the lower lead frame each further has a metal film electroplated thereon.

15 (original). The semiconductor packaging structure as claimed in claim 10, wherein the cover is a  
transparent cover.

16 (original). The semiconductor packaging structure as claimed in claim 10, wherein the cover is a metal cover.

17 (original). The semiconductor packaging structure as claimed in claim 13, wherein the cover is a transparent cover.

18 (original). The semiconductor packaging structure as claimed in claim 13, wherein the cover is a metal cover.

Claims 19-20 (cancelled).